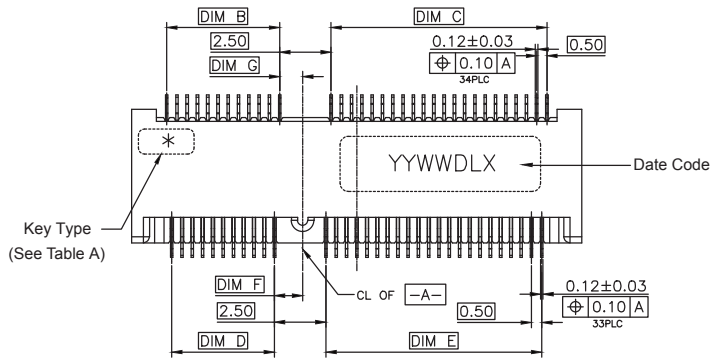
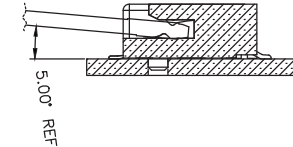


Isometric View



Recommended Card Insertion Angle

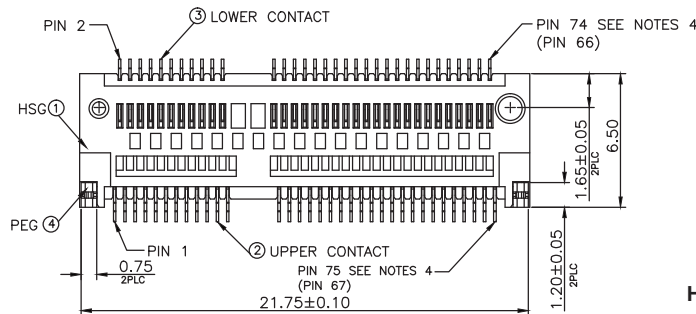
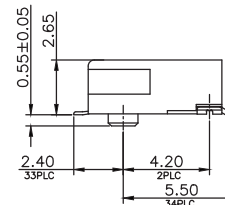
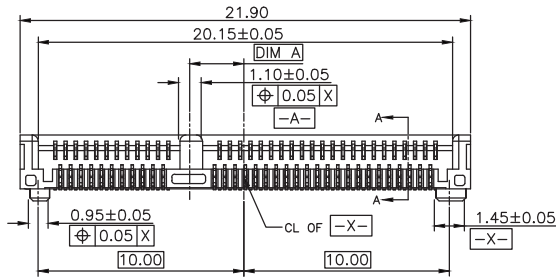


Table A : Keying Type & Code

KEY NAME	CODE NO.	DIM A	DIM B	DIM C	DIM D	DIM E	DIM F	DIM G
KEY A	00	6.625	1.5	14.5	1.0	14.5	1.375	1.125
KEY B	01	5.625	2.5	13.5	2.0	13.5	1.375	1.125
KEY C	02	4.625	3.5	12.5	3.0	12.5	1.375	1.125
KEY D	03	3.625	4.5	11.5	4.0	11.5	1.375	1.125
KEY E	04	2.625	5.5	10.5	5.0	10.5	1.375	1.125
KEY F	05	1.625	6.5	9.5	6.0	9.5	1.375	1.125
KEY G	06	-1.125	9.0	7.0	9.0	6.5	1.125	1.375
KEY H	07	-2.125	10.0	6.0	10.0	5.5	1.125	1.375
KEY J	08	-3.125	11.0	5.0	11.0	4.5	1.125	1.375
KEY K	09	-4.125	12.0	4.0	12.0	3.5	1.125	1.375
KEY L	10	-5.125	13.0	3.0	13.0	2.5	1.125	1.375
KEY M	11	-6.125	14.0	2.0	14.0	1.5	1.125	1.375

HOW TO ORDER:

M	2	0	0	-	0	1	X	X	-	6	0	X	X	-	Z	HF
NUMBER OF CONTACTS: 01 - 67 Contacts							KEY TYPE CODE 01 thru 11 See Table A (2nd Column) Example: Key M Code =11		HEIGHT OPTION: 6 - 2.65mm		CONTACT AREA PLATING: 0 - Full Au Flash 1 - 5µ" Au 2 - 10µ" Au 3 - 15µ" Au 4 - 30µ" Au		PACKAGING: 0 - Insertion Slot Forward 32mm Carrier Tape Width 1 - Insertion Slot Forward 44mm Carrier Tape Width 2 - Insertion Slot Backward 32mm Carrier Tape Width 4 - Insertion Slot Backward 44mm Carrier Tape Width			RoHS COMPLIANT HALOGEN FREE

MATERIAL:

HOUSING: High Temp Thermo Plastic UL94V-0, Black
SOLDER LATCH (PEG): Stainless Steel; 80u" Matte tin plating
over 50 u: Nickel
CONTACT: Copper Alloy
CONTACT PLATING: Specified Au Thickness in Contact Area
50u" Nickel Sub-Plate ; Au flash plating on solder tails.
See Contact Area Plating Option



LEAD FREE



Rev	Drawn	Checked	Approved	Date
0	Issued	B.S.	S.M.	10/13/16

SMP TECHNOLOGY, INC.

NGFF Connector ; 2.65mm Height

TOL. DEC. .X +/- 0.25 .XX +/- 0.15

ANGLE +/- 3°

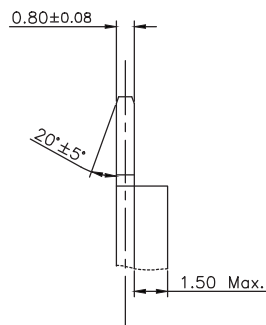
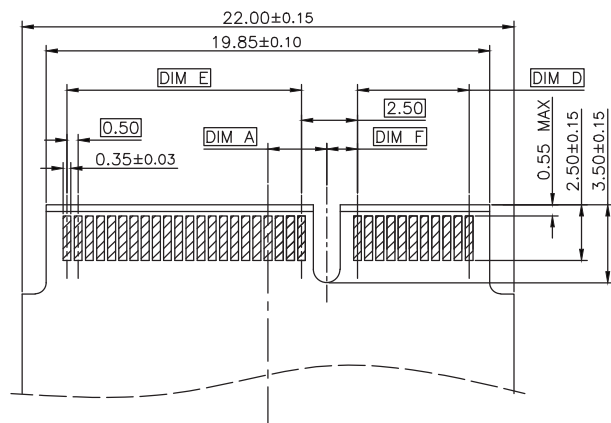
UNIT: mm

P/N: M200-01XX-60XX-ZHF

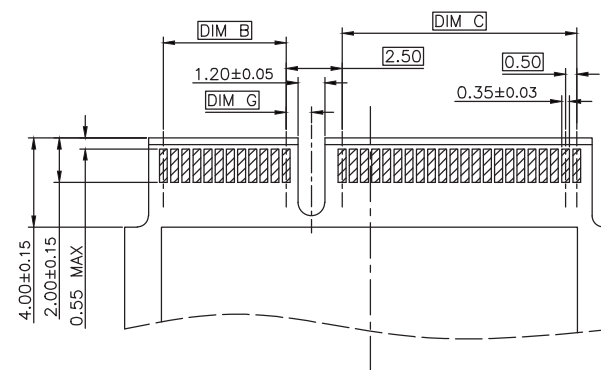
Pg: 1 of 6

Card Module PCB Layout

Bottom Side



Top Side



Recommended PCB Layout for Connector

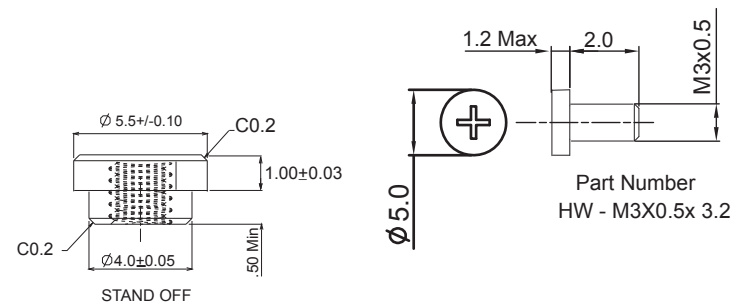
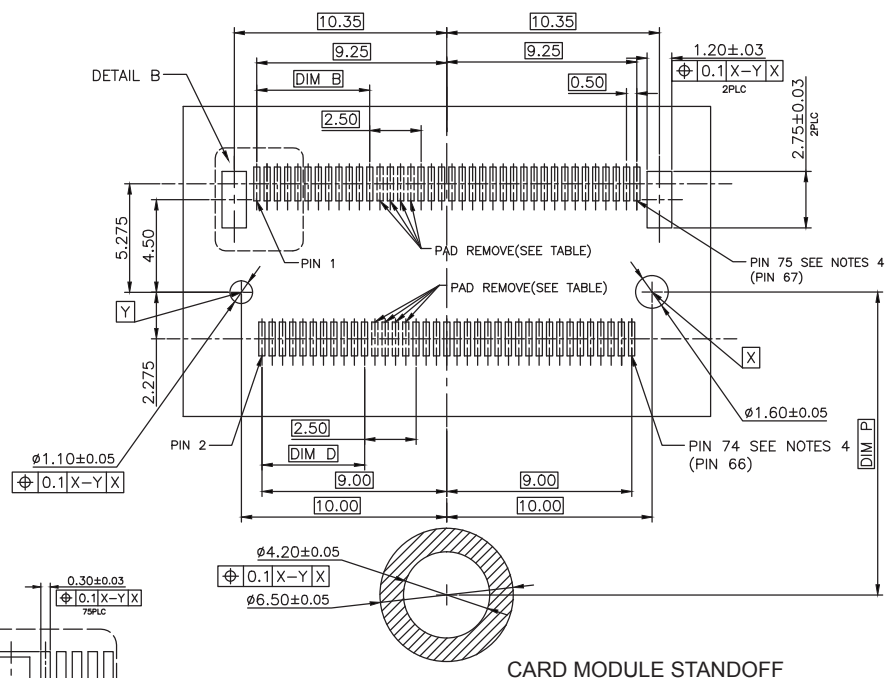


Table A : Keying Type & Code

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KEY K	09	-4.125	12.0	4.0	12.0	3.5	1.125	1.375
KEY L	10	-5.125	13.0	3.0	13.0	2.5	1.125	1.375
KEY M	11	-6.125	14.0	2.0	14.0	1.5	1.125	1.375

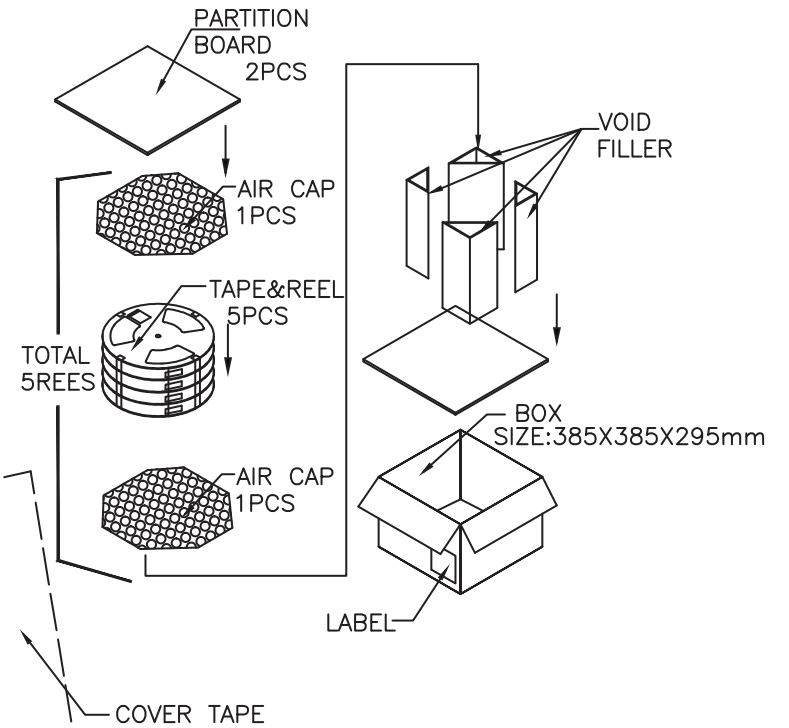
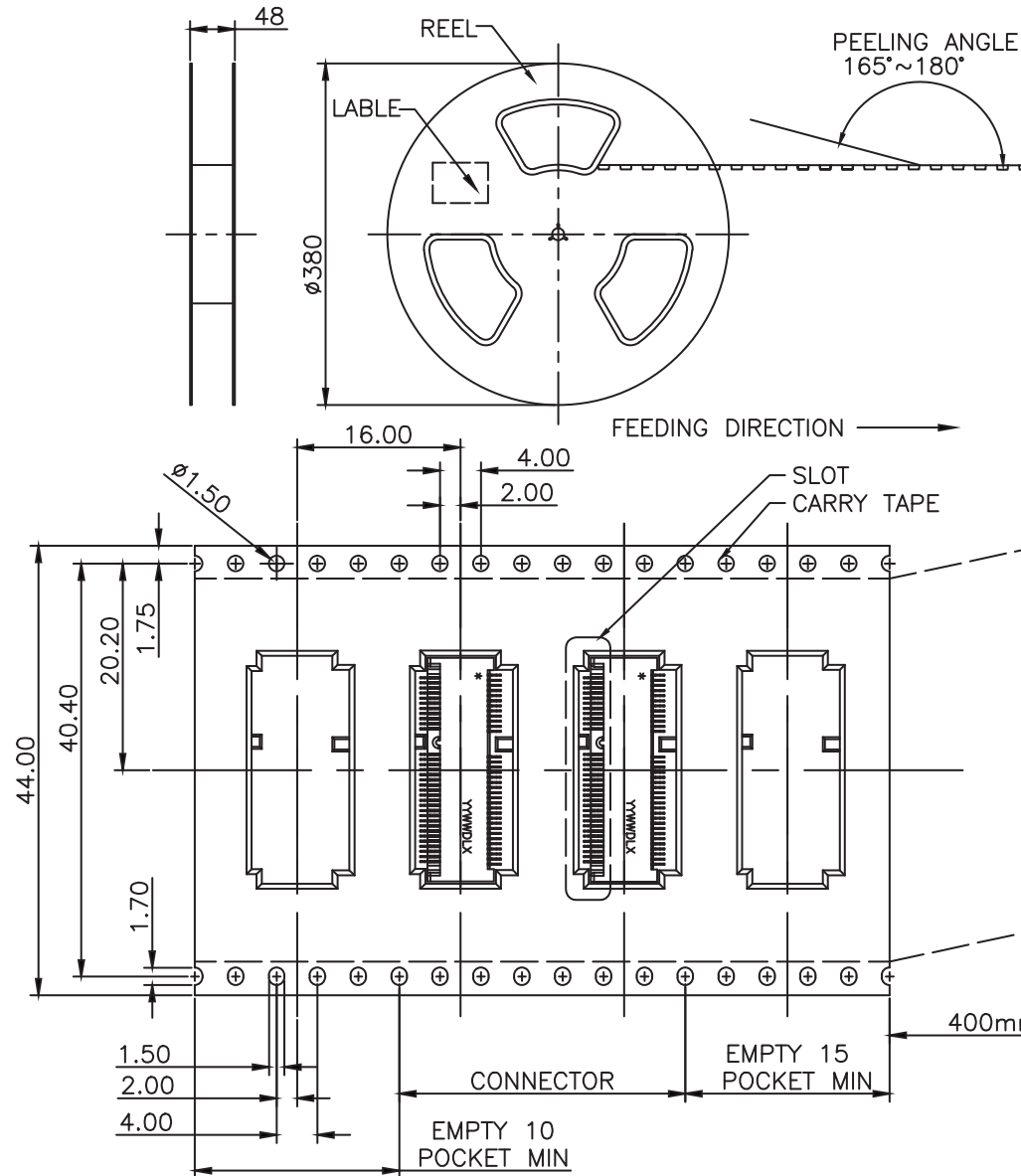
Card Module Length

MODULE TYPE	DIM P
3030	28.25
3042	40.25
2230	28.25
2242	40.25
2260	58.25
2280	78.25
22110	108.25

SMP TECHNOLOGY, INC.

NGFF Connector ; 2.65mm Height

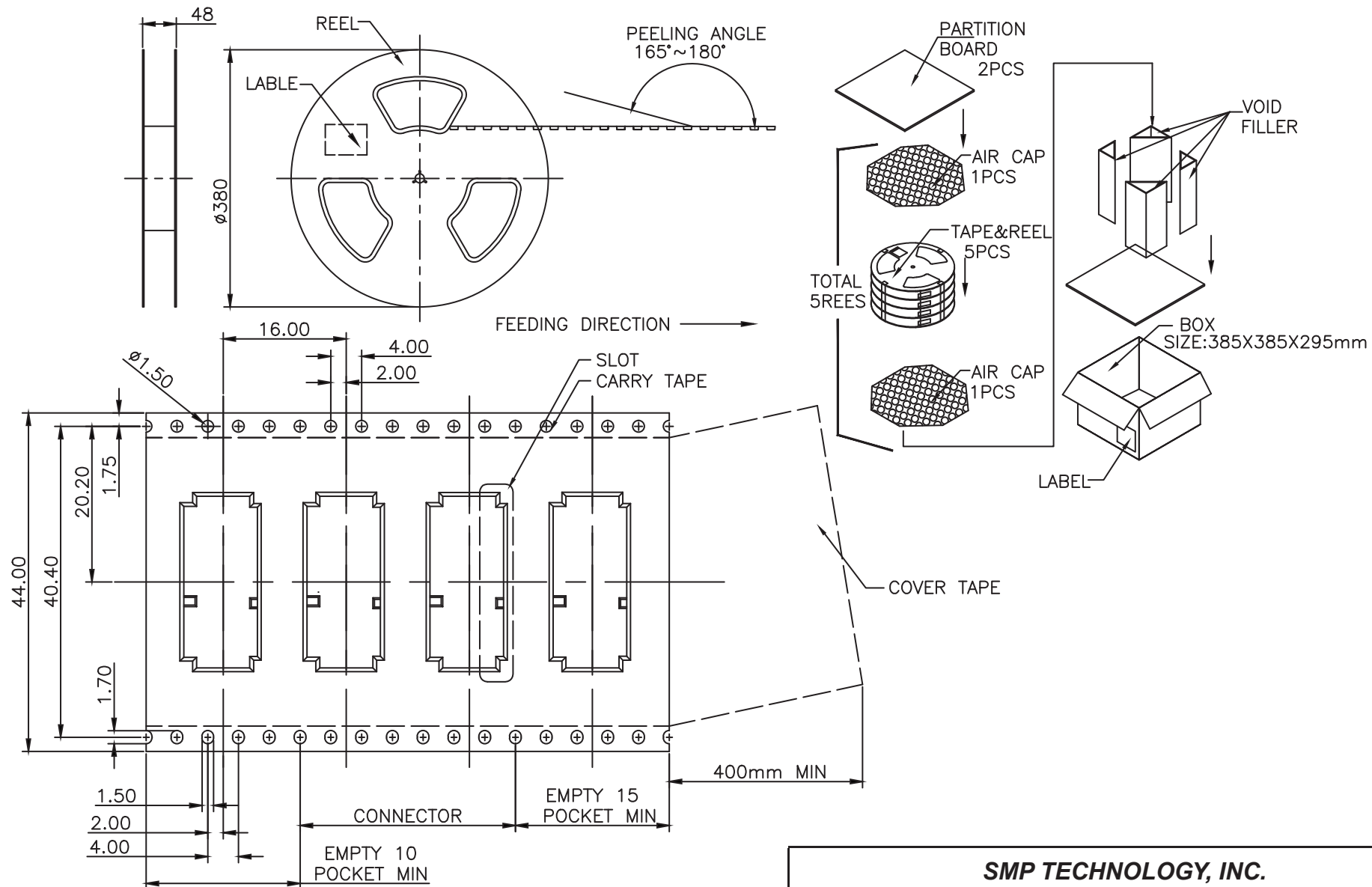
EMBOSS WIDTH 44mm, SLOT BACKWARD



SMP TECHNOLOGY, INC.

NGFF Connector ; 2.65mm Height

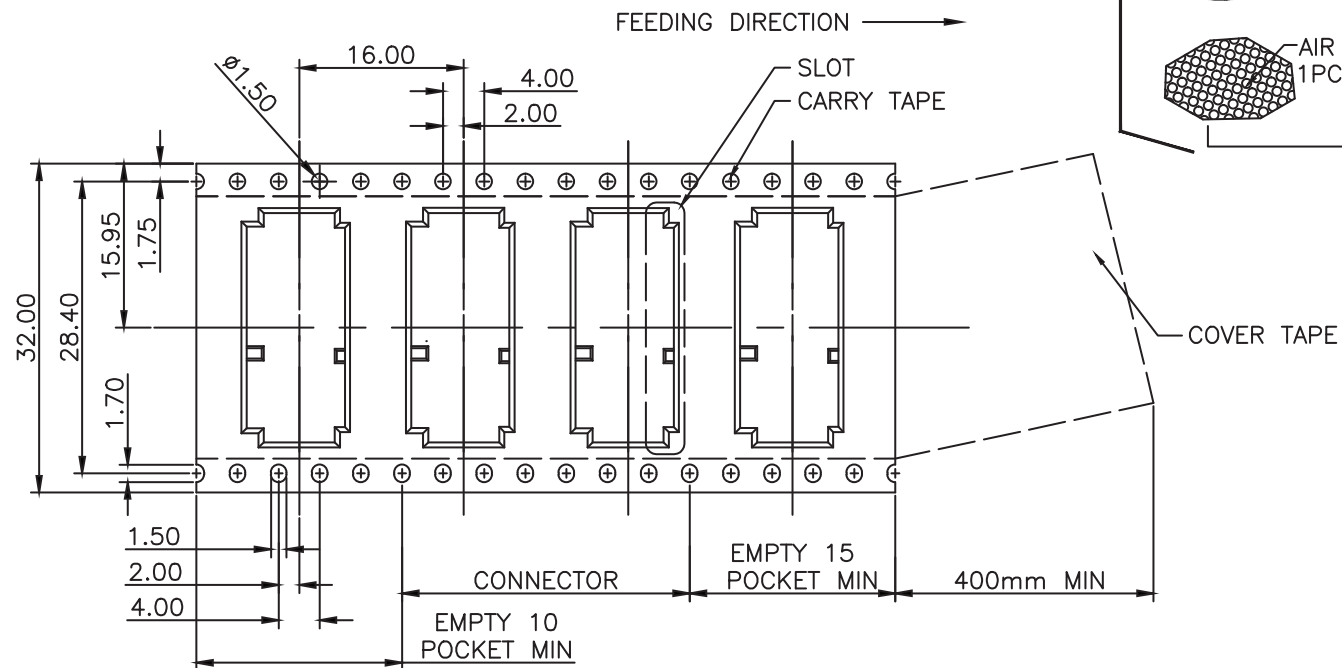
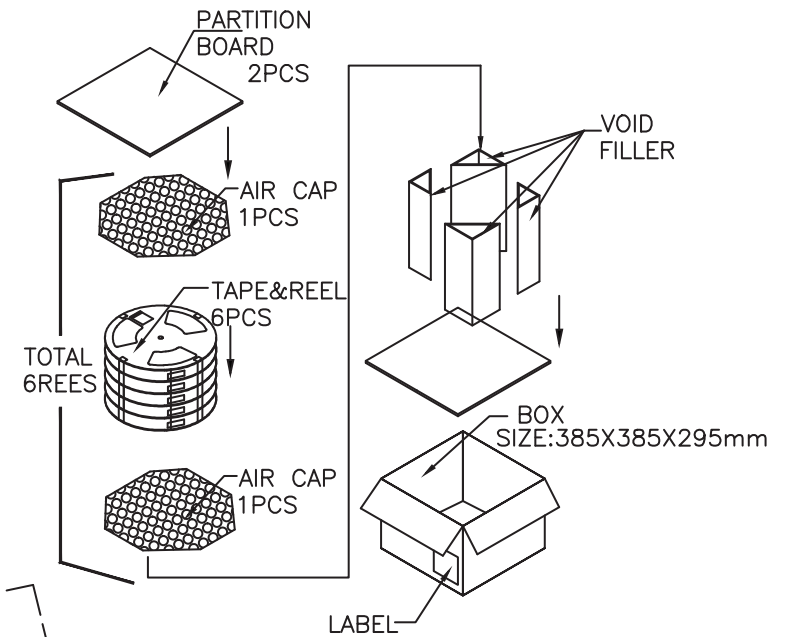
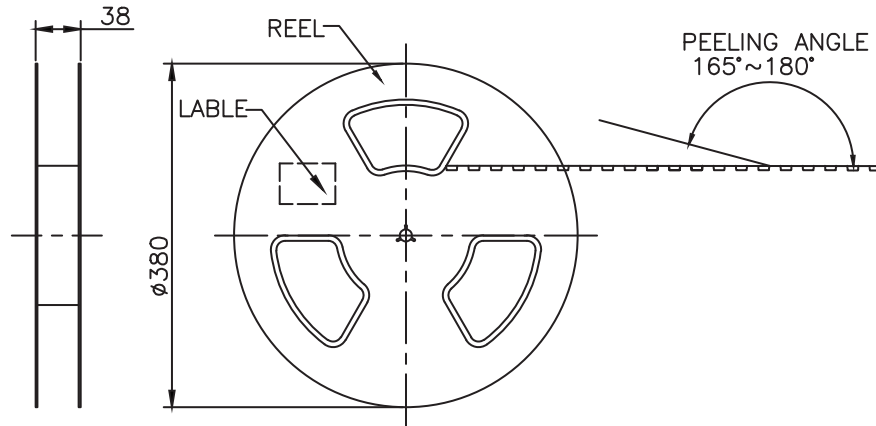
EMBOSS WIDTH 44mm, SLOT FORWARD



SMP TECHNOLOGY, INC.

NGFF Connector ; 2.65mm Height

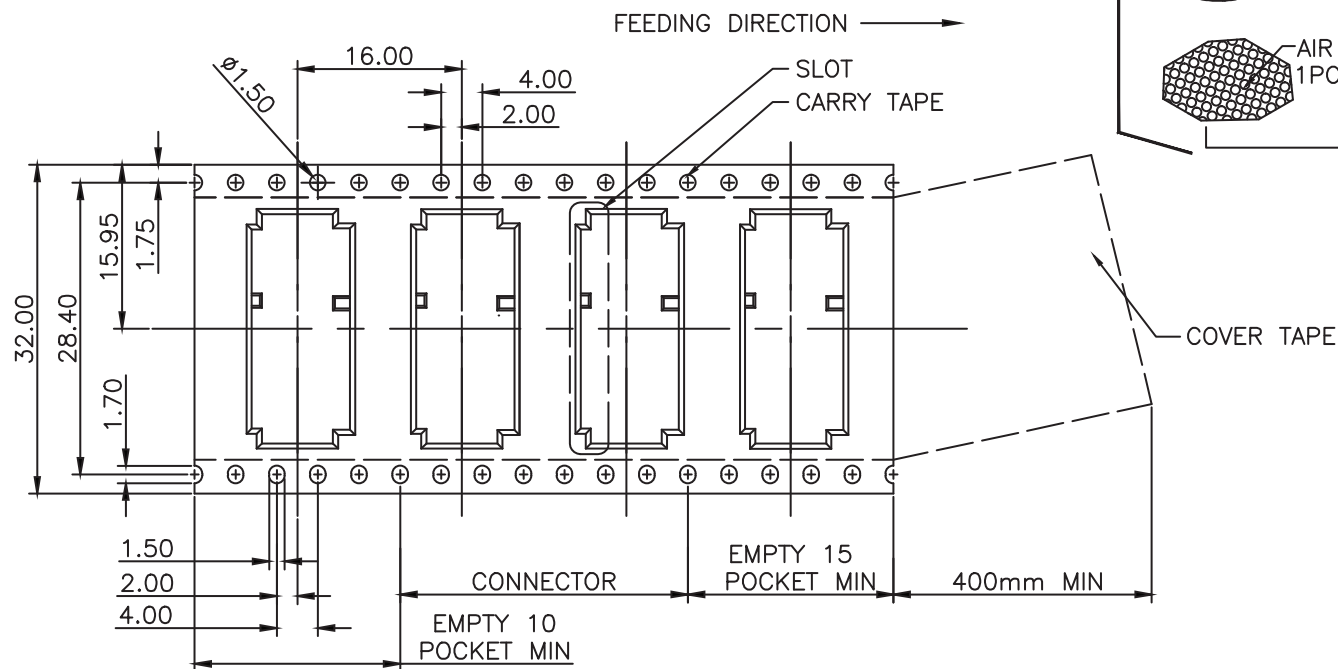
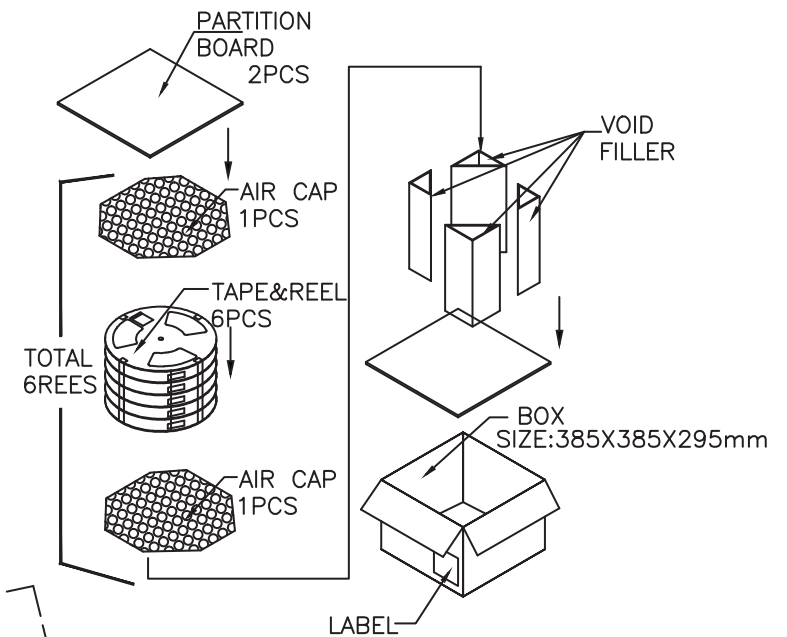
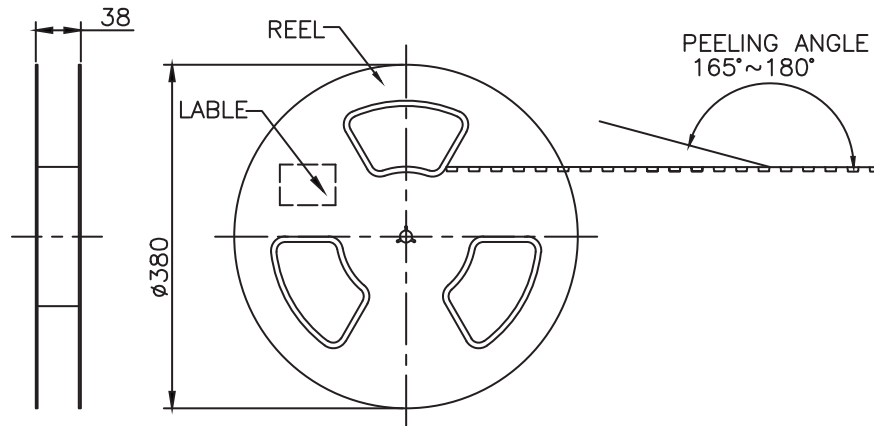
EMBOSS WIDTH 32mm, SLOT FORWARD



SMP TECHNOLOGY, INC.

NGFF Connector ; 2.65mm Height

EMBOSS WIDTH 32mm, SLOT BACKWARD



SMP TECHNOLOGY, INC.

NGFF Connector ; 2.65mm Height